

3-V, 10-BIT, 40-MSPS AREA CCD ANALOG FRONT-END

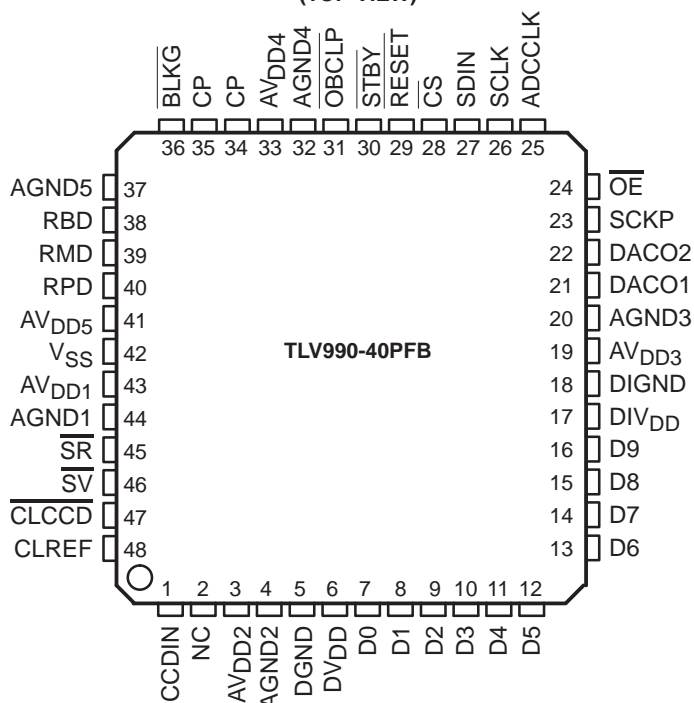
SLAS326A – JANUARY 2001 – REVISED MARCH 2004

features

- Single-Chip CCD Analog Front-End
- 10-Bit, 40-MSPS[†], A/D-Converter Single 3-V Supply Operation
- Very Low Power: 200 mW Typical, 2-mW Power-Down Mode
- Differential Nonlinearity Error: $< \pm 0.6$ LSB Typical
- Integral Nonlinearity Error: $< \pm 1.75$ LSB Typical
- Programmable Gain Amplifier (PGA) With 0-dB to 36-dB Gain Range (0.045 dB/Step)
- Automatic or Programmable Optical Black Level and Offset Calibration With Digital Filter and Bad Pixel Limits
- Additional DACs for External Analog Setting
- Serial Interface for Register Configuration
- Internal-Reference Voltages
- 48-Pin TQFP Package

application

- Digital Still Camera
- Video Camcorder

PFB PACKAGE
(TOP VIEW)

description

The TLV990-40 is a complete CCD and video signal processor/digitizer designed for digital still camera and video camcorder applications.

The TLV990-40 performs all the analog-processing functions necessary to maximize the dynamic range, corrects various errors associated with the CCD sensor, and then digitizes the results with an on-chip high-speed analog-to-digital converter (ADC).

The key components of the TLV990-40 include: an input clamp circuit for CCD and analog video signals, a correlated double sampler (CDS), a programmable-gain amplifier (PGA) with 0 to 36-dB gain range, two internal digital-to-analog converters (DAC) for automatic or programmable optical black level and offset calibration, a 10-bit, 40-MSPS pipeline ADC, a parallel data port for easy microprocessor interface, a serial port for configuring internal control registers, two additional DACs for external system control, and internal reference voltages.

Designed in advanced CMOS process, the TLV990-40 operates from a single 3-V power supply with a normal power consumption of 200 mW at 40 MSPS, and 2 mW in power-down mode.

Its very high throughput rate, single 3-V operation, very low-power consumption, and fully-integrated analog processing circuitry make the TLV990-40 an ideal CCD and video signal-processing solution for electronic video-camcorder applications.

This device is available in a 48-pin TQFP package and is specified over a -20°C to 75°C operating-temperature range.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

[†]The test register must be set to 1011 for 40 MSPS operation.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS
INSTRUMENTS**

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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TLV990-40PFB	NRND	TQFP	PFB	48	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-20 to 75	TLV990-40	
TLV990-40PFBG4	NRND	TQFP	PFB	48	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-20 to 75	TLV990-40	

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

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(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

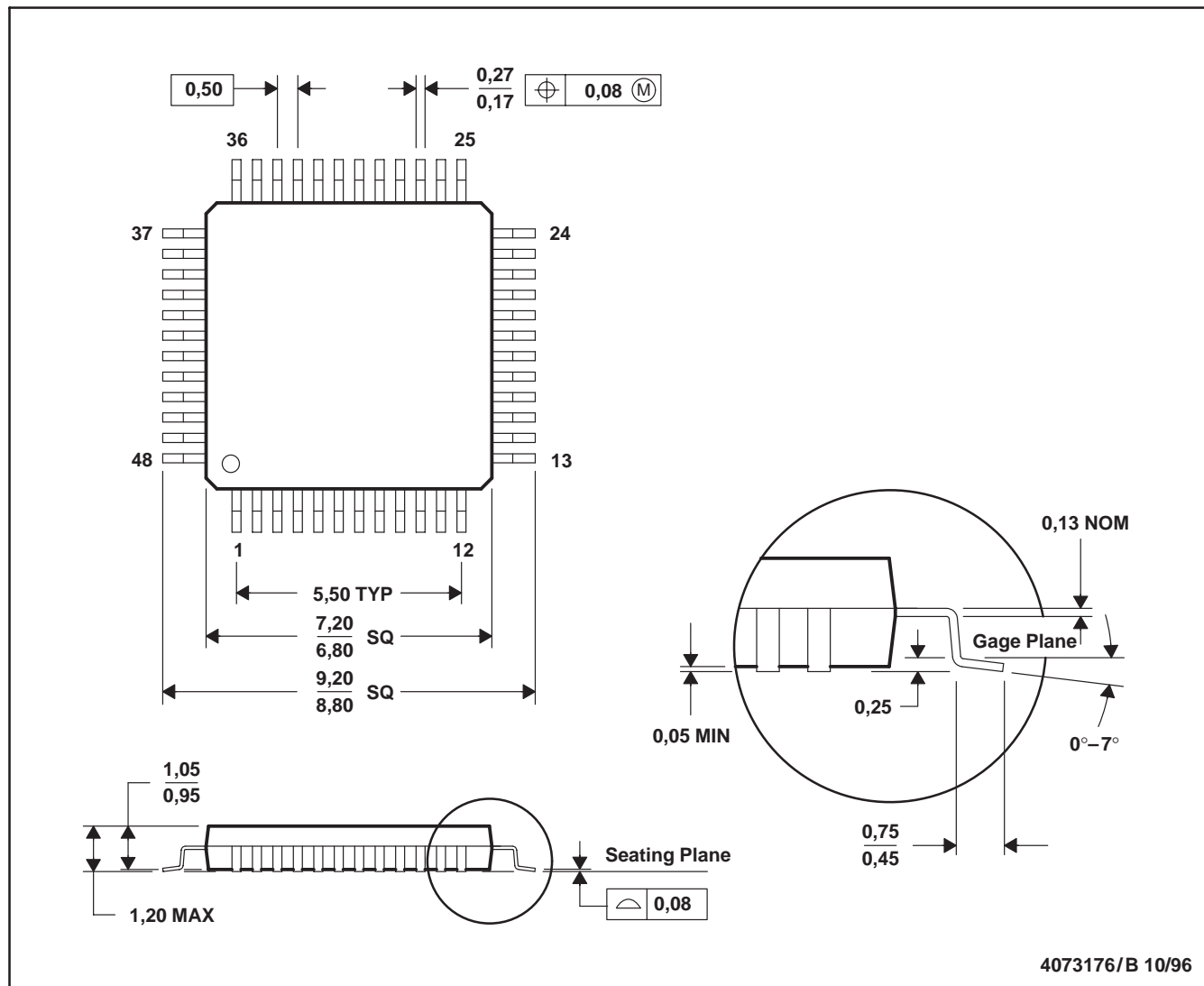
(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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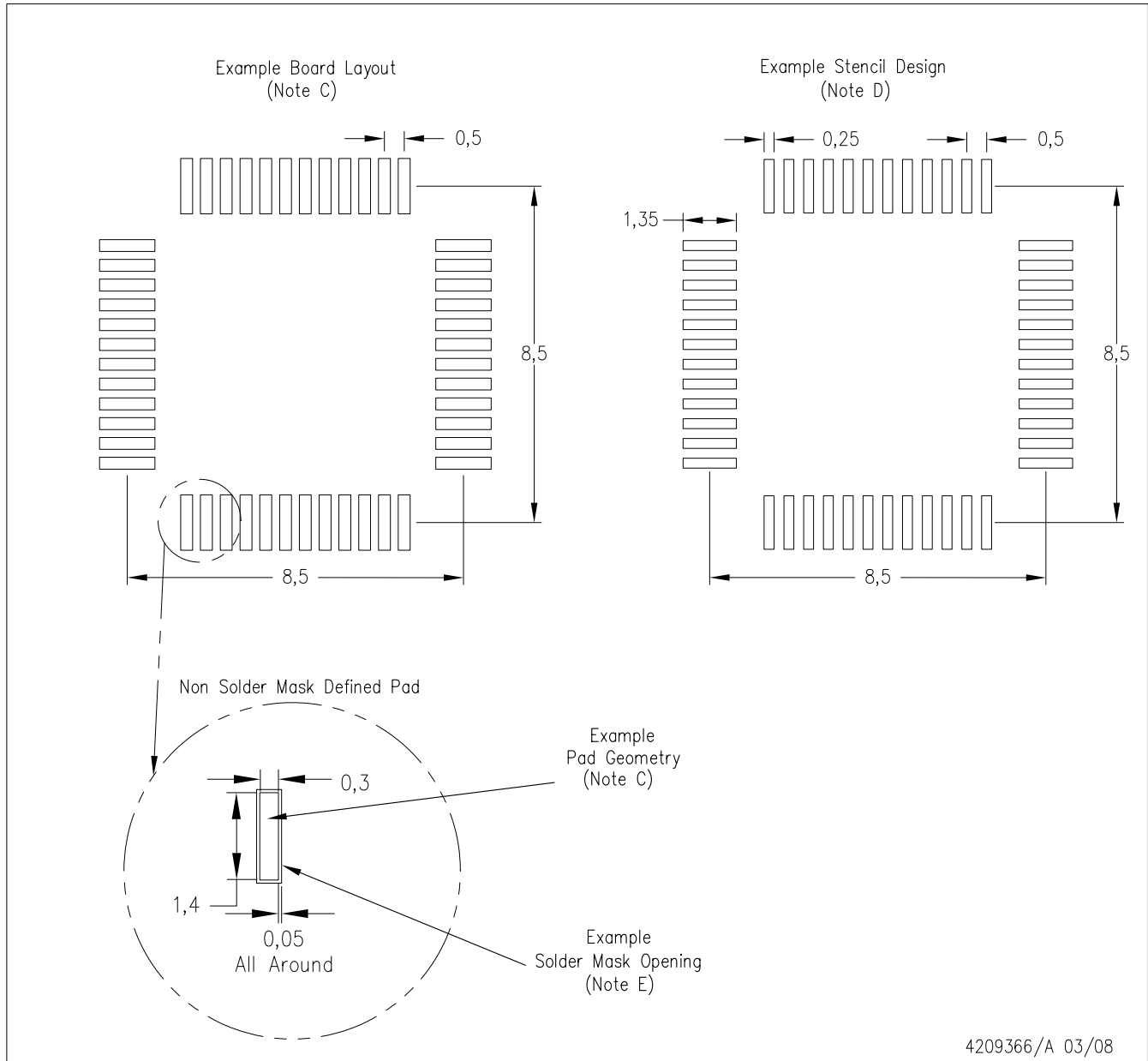
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PFB (S-PQFP-G48)

PLASTIC QUAD FLATPACK



PFB (S-PQFP-G48)



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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